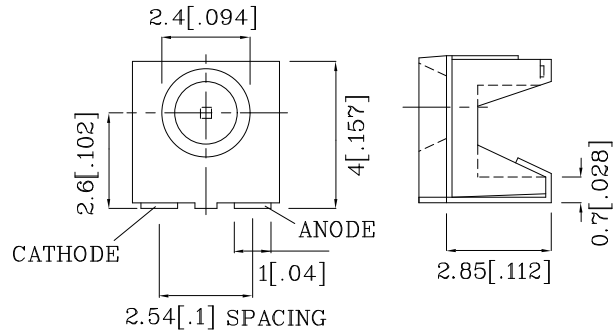
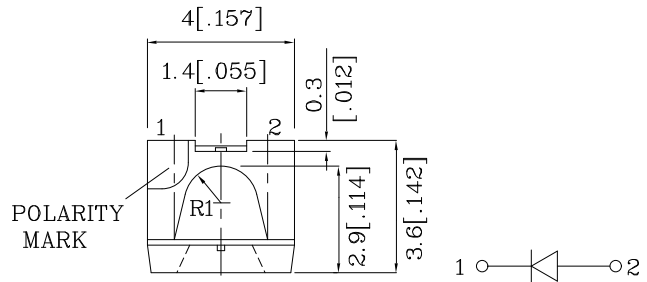


Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Moisture sensitivity level : level 3.
- Package : 500pcs / reel.
- RoHS compliant.



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PD	62.5	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		MG (GaP)	Unit
Forward Voltage (Typ.) (IF=20mA)	VF	2.2	V
Forward Voltage (Max.) (IF=20mA)	VF	2.5	V
Reverse Current (Max.) (VR=5V)	IR	10	uA
Wavelength of Peak Emission (Typ.) (IF=20mA)	λP	565	nm
Wavelength of Dominant Emission (Typ.) (IF=20mA)	λD	568	nm
Spectral Line Full Width At Half-Maximum (Typ.) (IF=20mA)	$\Delta\lambda$	30	nm
Capacitance (Typ.) (VF=0V, f=1MHz)	C	15	pF

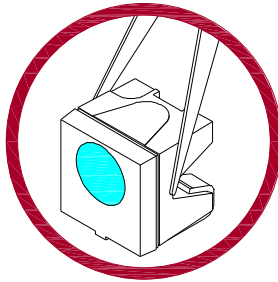
Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (IF=20mA)		Wavelength nm λP	Viewing Angle 2 θ 1/2
				min.	typ.		
XZMG67S	Green	GaP	Water Clear	10	24	565	120°

Handling Precautions

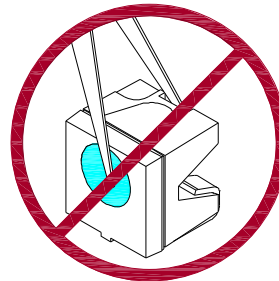
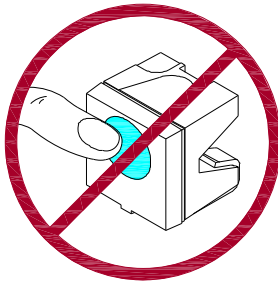
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

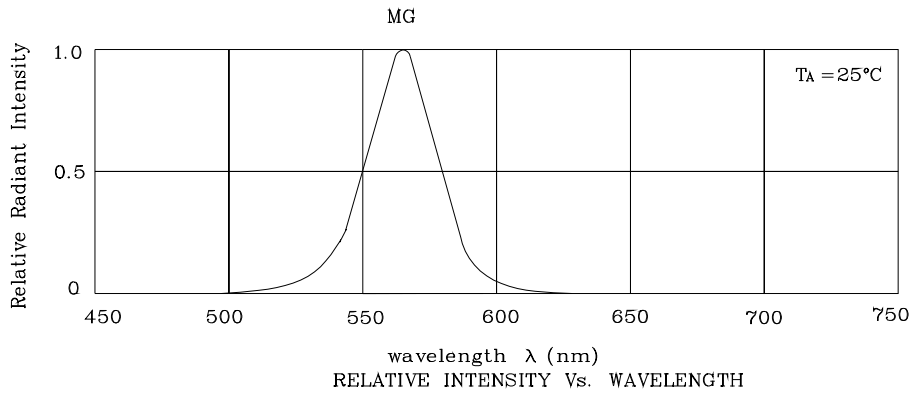
As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.

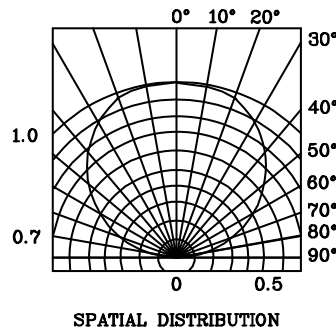
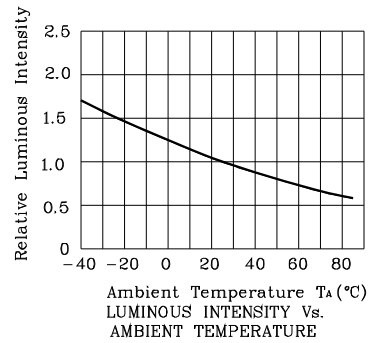
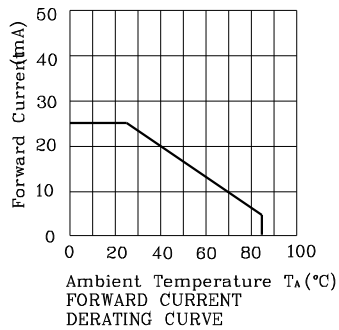
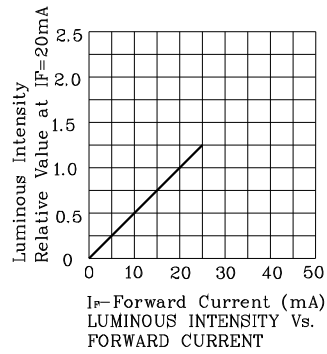
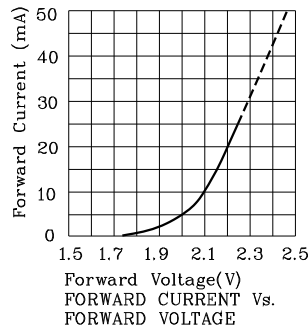


2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.

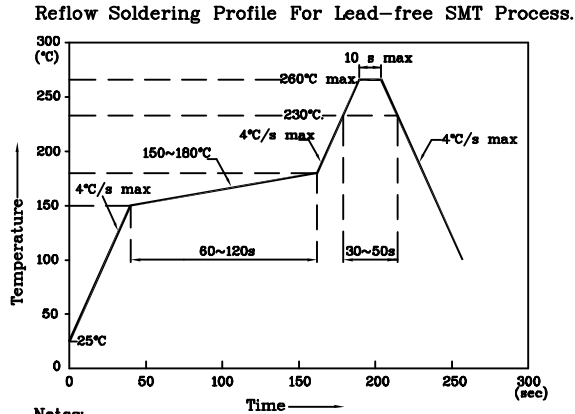




❖ MG



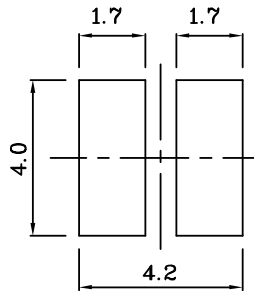
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.



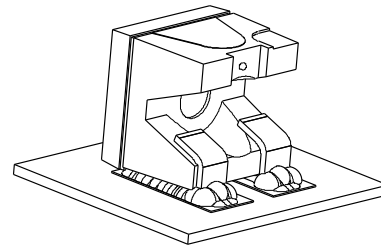
Notes:

1. Maximum soldering temperature should not exceed 260°C
2. Recommended reflow temperature: 145°C~260°C
3. Do not put stress to the epoxy resin during high temperatures conditions

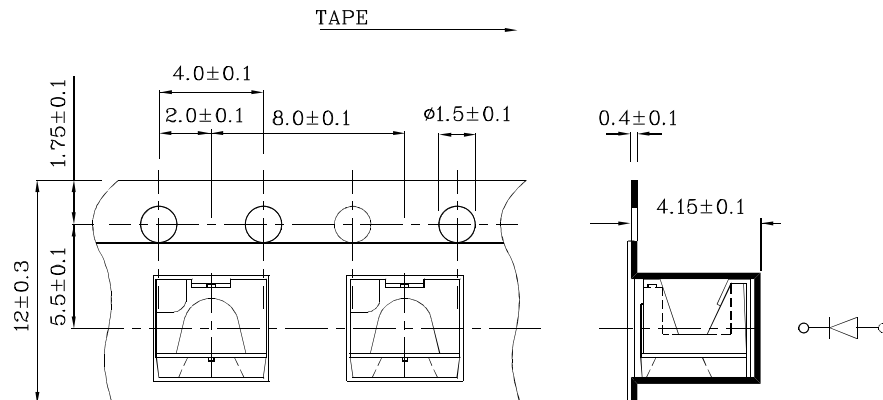
❖ Recommended Soldering Pattern
(Units : mm;Tolerance:± 0.1)



❖ The device has a single mounting surface. The device must be mounted according to the specifications.



❖ Tape Specification (Units : mm)



Remarks:

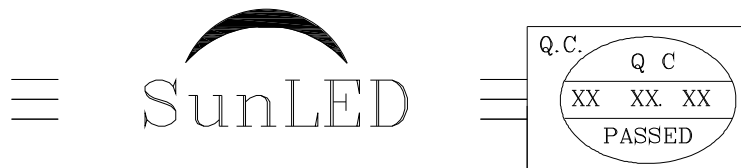
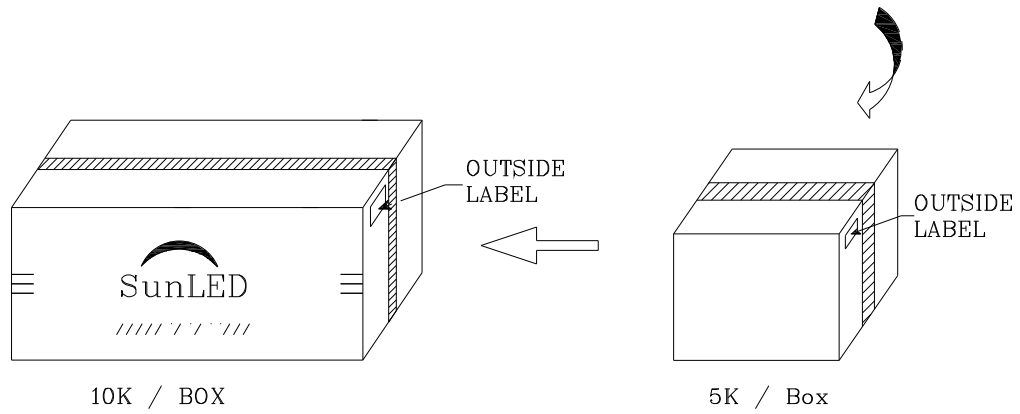
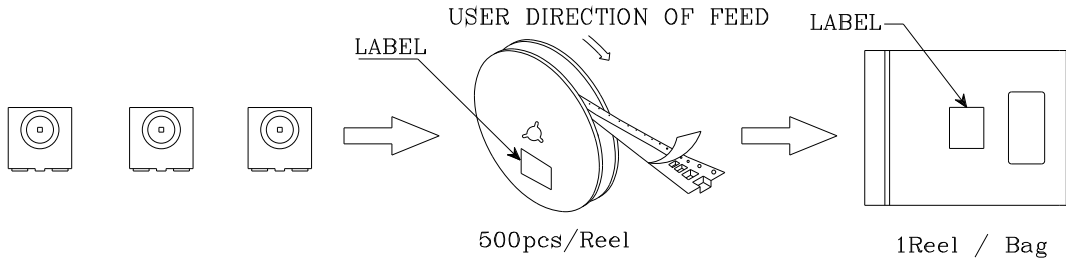
If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux or wavelength), the typical accuracy of the sorting process is as follows:


1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XZMG67S



P/N0 : XZxx67x	
QTY : 500 pcs	CODE: XXX
S/N : XX	
LOT NO:	
 xxxxxxxxxxxxxxxxxxxxxxxx	
RoHS Compliant	